

KC-LINK with KONNEKT Technology

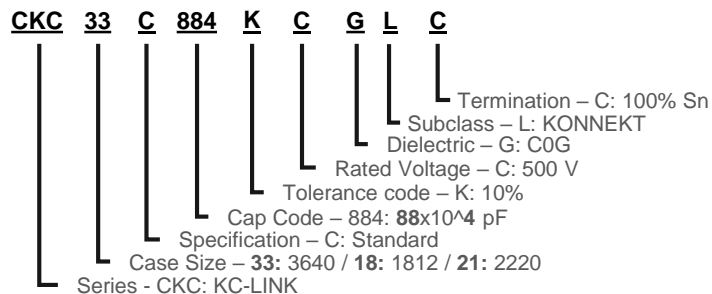
Overview

KC-LINK™ with KONNEKT™ technology surface mount capacitors are designed for high-efficiency and high-density power applications. KONNEKT high density packaging technology uses an innovative Transient Liquid Phase Sintering (TLPS) material to create a surface mount multi-chip solution for high density packaging.

Benefits

- Commercial and Automotive Grade (AEC-Q200)
- Stable capacitance with temperature, frequency, and voltage
- Ultra-low ESR: < 2.5 mΩ
- Ultra-low ESL: 0.45 nH
- Surface mount capable with standard reflow
- No piezoelectric noise

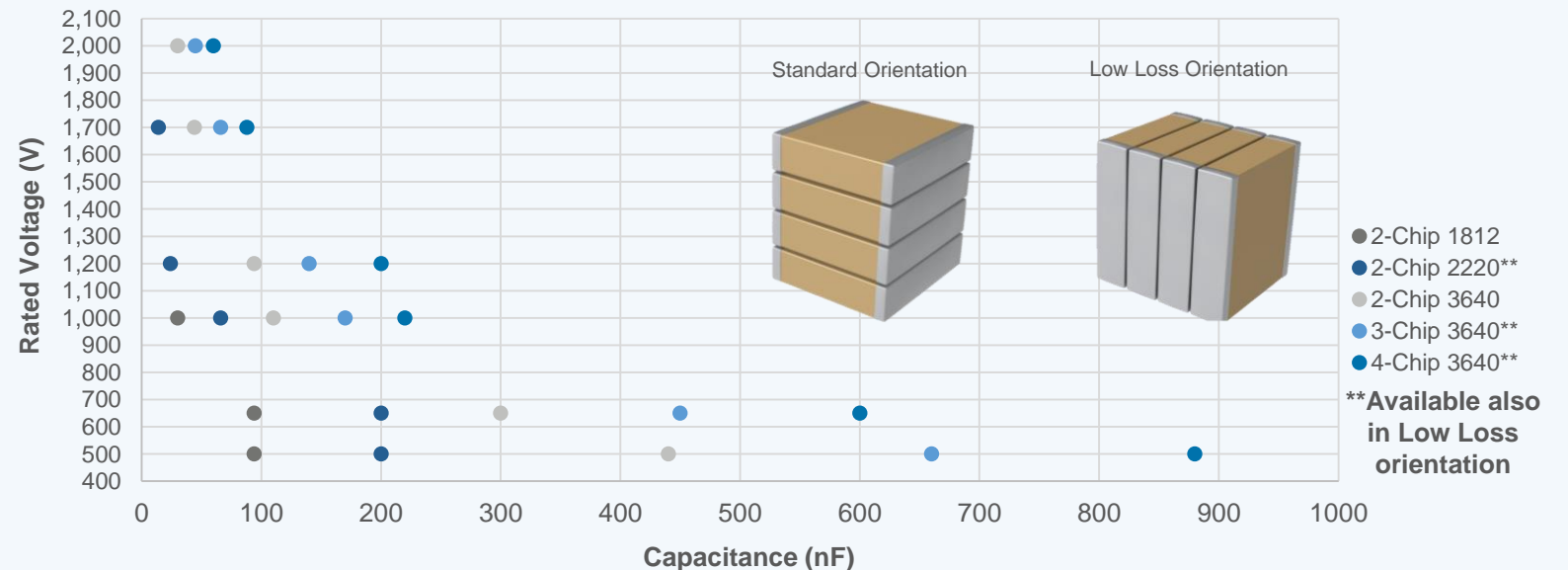
Part Number System



Electrical Characteristics

Operating Temperature	-55°C to +150°C
Rated Capacitance	14 nF – 880 nF (±10% tol.)
Typical ESR at 100 kHz	< 2.5 mΩ max
Rated Voltage	500 V – 2,000 V

KC-LINK with KONNEKT Selection Guide



Applications

- Wide bandgap (WBG), silicon carbide (SiC) and gallium nitride (GaN) systems
- EV/HEV (drive systems, charging)
- LLC resonant converters
- Switched tank converters
- Data centers
- Wireless charging systems
- Power converters
- DC link